

## ABSTRACT

Optoelectronic packages and methods to simultaneously couple an optoelectronic chip to a waveguide and substrate using conventional flux soldering processes are disclosed. A disclosed optoelectronic package includes a substrate, a waveguide mounted on the substrate, an optoelectronic chip having electrically conductive contacts coupled to the substrate via a metallic solder and an optical element located on the optoelectronic chip and coupled to the waveguide via an optical solder which protects the optical element during a metallic soldering of the optoelectronic chip to the substrate.